



Silicon Motion, Inc.

SM32X Test Program and ISP Release Note

**SM3257 Test Program and ISP Release Note:**

Release Date	ISP Version	ISP Check Sum	Test AP Version	Description
2010/06/07	SM3257AA 2010-06-07	SM3257AAISP 0x005ABF6E	V2.03.28 V5 10/06/07 build	1. SM3257AAISP support Samsung 32nm TLC bucket00 flash K9ABG08U0A, K9BCG08U1A and K9CDG08U5A 2. SM3257AAISP support Samsung 27nm MLC K9GBG08U0A 3. SM3257AAISP-bucket01 support Samsung 32nm TLC bucket01 flash K9ABG08U0A, K9BCG08U1A and K9CDG08U5A.
2010/07/02	SM3257AA 2010-07-02	SM3257AAISP 0x005D3C3E SM3257AAISP-bucket01 0x005D12F0	V2.03.29 V3 10/07/02 build	1. SM3257AAISP support Samsung 32nm MLC 2. SM3257AAISP support Intel/Micron L74A 3. SM3257AAISP support Intel/Micron L73A 4. SM3257AAISP enhance suddenly power cycling protection 5. SM3257AAISP-bucket01 enhance suddenly power cycling protection 6. SM3257AAISP support Hynix 26nm MLC. 7. MP tool fixed device disconnection issue when MP tool initial card.
2010/08/18	SM3257AA 2010-08-09 SM3257AA 2010-08-16 SM3257AA 2010-08-09	SM3257AAISP 0x005D3AEF SM3257AAISP-bucket01 0x005D9003 SM3257AAISP-HY32 0x005D8449	V2.03.31 V1 10/08/18 build	1. SM3257AAISP, SM3257AAISP-bucket01 and SM3257AAISP-HY32 fixed power cycling issue to cause system block occurs ECC fail. 2. SM3257AAISP, SM3257AAISP-bucket01 and SM3257AAISP-HY32 fixed build link block issue when plug in UFD. 3. SM3257AAISP support Hynix 26nm MLC H27UCG8T2MYR. 4. SM3257AAISP-HY32 support Hynix 32nm TLC H27UBG8M2A.



				<ol style="list-style-type: none"> MP tool fixed update ISO issue (CDROM + Public mode change to Public only mode without do-pretest) . MP tool add QC function which check capacity and used space. MP tool add Multiple Erase all function.
2010/09/23	SM3257AA	SM3257AAISP.bin	V 2.03.31 v13	<ol style="list-style-type: none"> SM3257AAISP fixed Cache read and 2Plane Read to cause burn in fail without mark bad block for Hynix 26nm MLC H27UCG8T2MYR supporting. SM3257AAISP adjust clock rate from 60MHz to 48MHz for Hynix 32nm MLC 16Gbit H27UAG8T2BTR supporting. SM3257AAISP-HY32 fixed 2Plane Read cause burn-in fail issue for Hynix 32nm TLC HY27UBG8M2A. SM3257AAISP-bucket01 fixed Samsung framework, Getstatus, setfeature and clearfeature do endpoint halt for EP0. SM3257AAISP support Micron L74A new flash ID (2C 88 24 49) SM3257AAISP support Micron L72A MT29F16G08CBACA SM3257AAISP support new Led function when MP tool initialization SM3257AAISP support Micron L73A MT29F32G08CBACA with 1CE2Die bonding. MP tool support LED blinking when initial UFD device.
	2010-09-22	0x005E3C38	10/09/08	
	SM3257AA	SM3257AAISP-bucket01.bin		
	2010-09-14	0x005E5DAA		
	SM3257AA	SM3257AAISP-HY32.bin		
	2010-09-22	0x005E24B3		
2010/09/23	SM3257AA	SM3257AAISP.bin	V 2.03.32 v12	<ol style="list-style-type: none"> SM3257AAISP support Micron L72A MT29F16G08CBACA. SM3257AAISP support Intel L72A 29F16G083AME1.
	2010-09-22	0x005E3C38	10/10/15	



	SM3257AA 2010-09-14 SM3257AA 2010-09-22	SM3257AAISP-bucket01.bin 0x005E5DAA SM3257AAISP-HY32.bin 0x005E24B3		<ol style="list-style-type: none"> SM3257AAISP support Samsung 42nm SLC K9F8G08U0A. SM3257AAISP support Samsung 51nm MLC K9LBG08U0M. SM3257AAISP support Intel L74A new flash ID (89 88 24 CB) with 1CE2Die bonding. SM3257AAISP support Micron 34nm SLC MT29F32G08AFABA MP tool add FDD only function supporting MP tool Fixed MAC OS dismount device issue MP tool add QC function check disk label with all eleven characters.
2010/11/03	SM3257AA 2010-11-02 SM3257AA 2010-11-02 SM3257AA 2010-11-02	SM3257AAISP.bin 0x005EAD3A SM3257AAISP-bucket01.bin 0x005F0CDF SM3257AAISP-HY32.bin 0x005E9347	V 2.03.33 v1 10/11/02	<ol style="list-style-type: none"> SM3257AAISP support Hynix 32nm MLC H27UEG8YEA and H27UDG8V5A. SM3257AAISP fixed four die build link table issue when suddenly power cycling testing. MP tool fixed serial number issue with production date update. MP tool fixed show much bad block issue with non-initial card. MP tool fixed QC format issue. MP tool fixed QC check used space issue.
2010/11/22	SM3257AA 2010-11-18 SM3257AA 2010-11-02 SM3257AA 2010-11-18	SM3257AAISP.bin 0x005E9C5F SM3257AAISP-bucket01.bin 0x005F0CDF SM3257AAISP-HY32.bin 0x005E8599	V 2.03.34v12 10/11/22	<ol style="list-style-type: none"> SM3257AAISP support Intel L73A JS29F32G08AAME1 1CE2Die bonding (Flash ID: 89 88 05 CA) SM3257AAISP support Samsung 27nm MLC K9HDG08U1A SM3257AAISP support Intel L72A 29F16G08AAME1. SM3257AAISP support Samsung 42nm MLC K9PDG08U5D 16GB ULGA.



				<ul style="list-style-type: none">5. SM3257AAISP fixed Hynix 32nm MLC,26nm MLC and 32nm TLC write performance faster than read performance when WINSAT testing.6. MP tool add function reset hub with auto-handle.7. MP tool fixed QC check disk label issue with FAT32.
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